

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
UNITED STATES RECEIVING OFFICE (RO/US)

Applicant:	Francis Bourrieres, Clement Kaiser
Serial No.:	09/830253
Filed:	April 24, 2003
For:	Method For Making Electronic Modules With Ball Connector Or With Integrated Preforms Capable Of Being Soldered On A Printed Circuit And Implementing Device
Examiner:	Minh Trinh
Group Art Unit:	3729

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GROUP 3700

Box NON-FEE AMENDMENT
Assistant Commissioner of Patents
Washington, D.C. 20231

Docket No.: N48.2I-9735-US01

FACSIMILE TRANSMITTAL LETTER

TO: Examiner Trinh
FACSIMILE NO.: (703- 872-9302)
GROUP ART UNIT: 3729

DATE: March 6, 2003**TIME:** 12:01 P.M.**TOTAL NUMBER OF PAGES** (including cover sheet) 4

Dear Examiner:

In regard to the above-identified application, we are submitting the attached:
3 pages Amendment; and, 1 page VAS Facsimile Transmittal.

2. With respect to fees:

☒ No Fee is required.☐ Attached is check(s) in the amount for \$_____.☐ Charge any additional fees to Deposit Account No. 22-0350.

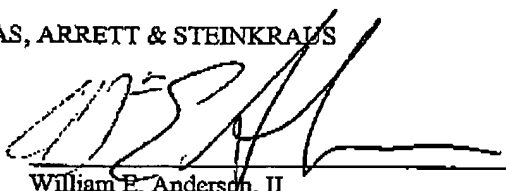
3. Notwithstanding paragraph 2 above, if any additional fees associated with this communication are required and have not otherwise been paid, including any fee associated with the Conditional Petition for Extension of Time, or any request in the accompanying papers for action which requires a fee as a petition to the Commissioner, please charge the additional fees to Deposit Account No. 22-0350. Please charge any additional fees or credit overpayment associated with this communication to the Deposit Account No. 22-0350.

Respectfully submitted by:

VIDAS, ARRETT & STEINKRAUS

Date: March 6, 2003

By:


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Robin Peddieson

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	Francis Bourrieres, Clement Kaiser
Application No.:	09/830253
Filed:	April 24, 2001
For:	Method For Making Electronic Modules With Ball Connector Or With Integrated Preforms Capable Of Being Soldered On A Printed Circuit And Implementing Device
Examiner:	Minh Trinh
Group Art Unit:	3729

Box Non-Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

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Amendment

Prior to examination, please amend the application *as filed* as follows:

In The Claims:

Please cancel claims 1-9.

Please add the following claims:

10. (New) Method for producing an electronic module in the shape of a ball housing combining a network of interconnection or shielding balls (7) or geometrically identical preforms and surface-mounted components (2) on the same side of a substrate (1), thus making the module directly connectable to a printed circuit (3), wherein:

soldering cream (8) is deposited simultaneously for the components and the interconnection or shielding balls located on the same surface;

the said components are transferred onto the corresponding mounting lands;

the interconnection balls are transferred collectively onto the lands of the same side intended for them by an appropriate device; and

a single reflow cycle permits simultaneous soldering of the components and the interconnection or shielding balls onto the substrate.

11. (New) Method as claimed in claim 10, wherein the soldering cream (8) is deposited via